

ULTRA-LOW PROFILE TERMINAL

TLH Mates with:

SLH

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TLH

SPECIFICATIONS

Insulator Material:

Black Liquid Crystal Polymer

Contact Material:

Copper Alloy

Plating:

Au over 50 μ" (1.27 μm) Ni

Current Rating:

2.1 A per pin

(2 pins powered)

Operating Temp Range:

-55 °C to +125 °C

RoHS Compliant:

Yes

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max

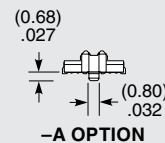
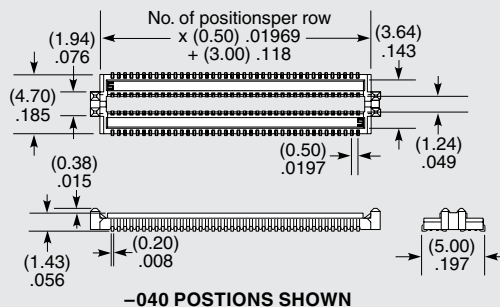
RECOGNITIONS



FILE NO. E111594

TLH	NO. OF POSITIONS	LEAD STYLE	PLATING OPTION	D	OPTION	OPTION
	-010, -020, -030, -040, -050 (Per Row)	-0.50 = 0.50 mm	-G = 10 μ" (0.25 μm) Gold in contact, Gold flash on tail		-A = Alignment Pin	-K = (3.00 mm) .118" DIA Polyimide Film Pick & Place Pad

-040 & -050 POSITIONS
PRELIMINARY



HIGH-SPEED CHANNEL PERFORMANCE

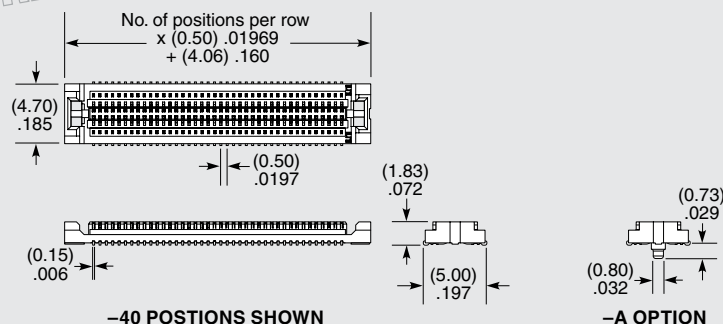
TLH/SLH @ 2 mm Mated Stack Height

Rating based on Samtec reference channel.

28
Gbps

SLH	NO. OF POSITIONS	LEAD STYLE	PLATING OPTION	D	OPTION	OPTION
	-010, -020, -030, -040, -050 (Per Row)	-1.50 = 1.50 mm	-G = 10 μ" (0.25 μm) Gold in contact, Gold flash on tail		-A = Alignment Pin	-K = (3.00 mm) .118" DIA Polyimide Film Pick & Place Pad

-040 & -050 POSITIONS
PRELIMINARY



Note: Some lengths,
styles and options are
non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.